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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







## **IGBT**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss.

#### **Features**

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- 5 µs Short–Circuit Capability
- These are Pb–Free Devices

#### **Typical Applications**

- Solar Inverters
- Uninterruptible Power Supplies (UPS)
- Welding

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	V <sub>CES</sub>	600	V
Collector current @ Tc = 25°C @ Tc = 100°C	I <sub>C</sub>	100 75	A
Diode Forward Current @ Tc = 25°C @ Tc = 100°C	I <sub>F</sub>	100 75	A
Diode Pulsed Current T <sub>PULSE</sub> Limited by T <sub>J</sub> Max	I <sub>FM</sub>	200	Α
Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>CM</sub>	200	Α
Short–circuit withstand time $V_{GE} = 15 \text{ V}, V_{CE} = 400 \text{ V}, $ $T_J \le +150 ^{\circ}\text{C}$	t <sub>SC</sub>	5	μS
Gate-emitter voltage	$V_{GE}$	±20	V
Transient gate-emitter voltage ( $T_{PULSE} = 5 \mu s$ , D < 0.10)		±30	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	595 265	W
Operating junction temperature range	TJ	–55 to +175	°C
Storage temperature range	T <sub>stg</sub>	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

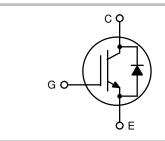
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

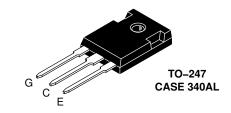


### ON Semiconductor®

www.onsemi.com

75 A, 600 V V<sub>CEsat</sub> = 1.70 V E<sub>OFF</sub> = 1.0 mJ





#### **MARKING DIAGRAM**



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
NGTB75N60FL2WG	TO-247 (Pb-Free)	30 Units / Rail

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.28	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	0.62	°C/W
Thermal resistance junction-to-ambient	$R_{ heta JA}$	40	°C/W

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC		•				
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V}, I_{C} = 500  \mu\text{A}$	V <sub>(BR)CES</sub>	600	_	-	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A, T <sub>J</sub> = 175°C	V <sub>CEsat</sub>	1.50 –	1.75 2.30	2.00	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 350 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 600 V V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 600 V, T <sub>J =</sub> 175°C	I <sub>CES</sub>	_ _	_ _	0.1 4.0	mA
Gate leakage current, collector–emitter short–circuited	V <sub>GE</sub> = 20 V , V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	_	200	nA
DYNAMIC CHARACTERISTIC		•		•		
Input capacitance		C <sub>ies</sub>	_	7500	_	pF
Output capacitance	V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	_	300	-	
Reverse transfer capacitance	1	C <sub>res</sub>	-	190	-	
Gate charge total		Q <sub>q</sub>	_	310	_	nC
Gate to emitter charge	V <sub>CE</sub> = 480 V, I <sub>C</sub> = 75 A, V <sub>GE</sub> = 15 V	Q <sub>ge</sub>	-	60	-	
Gate to collector charge	1	Q <sub>gc</sub>	_	150	_	
SWITCHING CHARACTERISTIC, INDUCT	TIVE LOAD	90		1		<u>l</u>
Turn-on delay time		t <sub>d(on)</sub>	_	110	_	ns
Rise time	1	t <sub>r</sub>	_	48	-	
Turn-off delay time	T <sub>J</sub> = 25°C	t <sub>d(off)</sub>	_	270	_	
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 75 \text{ A}$	t <sub>f</sub>	_	70	_	
Turn–on switching loss	$R_g = 10 \Omega$ $V_{GE} = 0 \text{ V/ } 15 \text{ V}$	E <sub>on</sub>	_	2.2	_	mJ
Turn-off switching loss	GE 3 W 13	E <sub>off</sub>	_	1.1	_	
Total switching loss		E <sub>ts</sub>	_	3.3	_	
Turn-on delay time		t <sub>d(on)</sub>	_	100	-	ns
Rise time	1	t <sub>r</sub>	_	50	_	
Turn-off delay time	T <sub>J</sub> = 150°C	t <sub>d(off)</sub>	_	280	_	
Fall time	$V_{CC} = 400 \text{ V, } I_{C} = 75 \text{ A}$ $R_{g} = 10 \Omega$ $V_{GE} = 0 \text{ V/ } 15 \text{ V}$	t <sub>f</sub>	_	100	_	
Turn-on switching loss		E <sub>on</sub>	_	2.8	_	mJ
Turn-off switching loss	1	E <sub>off</sub>	_	1.6	-	ĺ
Total switching loss	1	E <sub>ts</sub>	_	4.4	-	ĺ
DIODE CHARACTERISTIC		•		•		
Forward voltage	$V_{GE} = 0 \text{ V, } I_F = 75 \text{ A}$ $V_{GE} = 0 \text{ V, } I_F = 75 \text{ A, } T_J = 175^{\circ}\text{C}$	V <sub>F</sub>	1.70 -	2.20 2.40	2.90 -	V
Reverse recovery time	T <sub>.1</sub> = 25°C	t <sub>rr</sub>	_	80	-	ns
Reverse recovery charge	$I_J = 25^{\circ}C$ $I_F = 75 \text{ A, } V_R = 400 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu\text{s}$	Q <sub>rr</sub>	_	0.40	-	μC
Reverse recovery current		I <sub>rrm</sub>	_	8	-	Α
Reverse recovery time	T <sub>J</sub> = 175°C	t <sub>rr</sub>	_	143	-	ns
Reverse recovery charge	$I_F = 75 \text{ A}, V_R = 400 \text{ V}$	Q <sub>rr</sub>	_	1.45	-	μC
Reverse recovery current	$di_F/dt = 200 A/\mu s$	I <sub>rrm</sub>	_	16	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

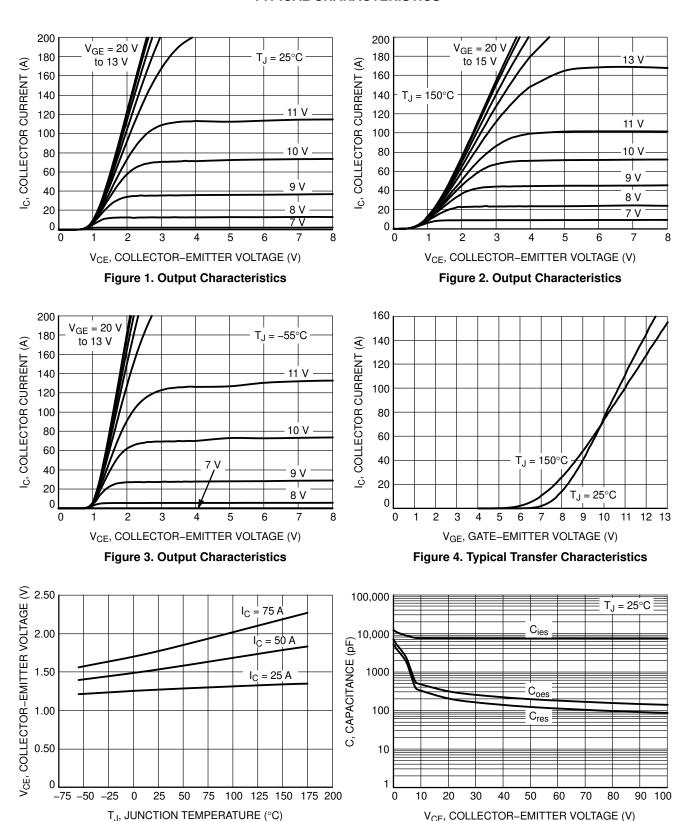


Figure 6. Typical Capacitance

Figure 5. V<sub>CE(sat)</sub> vs. T<sub>J</sub>

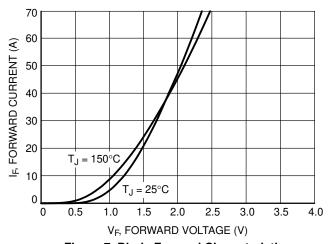


Figure 7. Diode Forward Characteristics

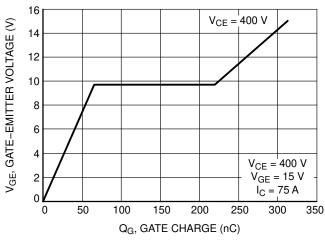


Figure 8. Typical Gate Charge

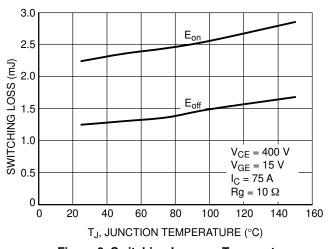


Figure 9. Switching Loss vs. Temperature

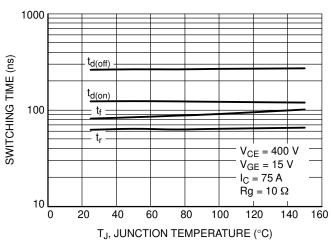


Figure 10. Switching Time vs. Temperature

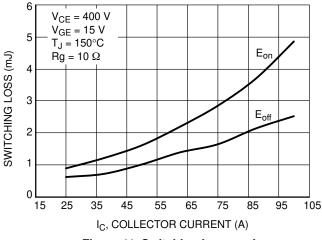


Figure 11. Switching Loss vs. I<sub>C</sub>

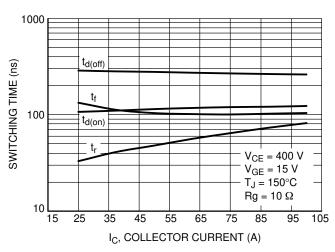


Figure 12. Switching Time vs. I<sub>C</sub>

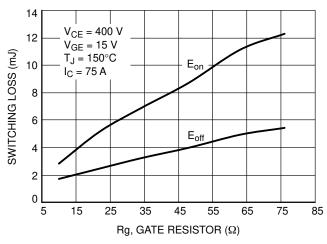


Figure 13. Switching Loss vs. Rg

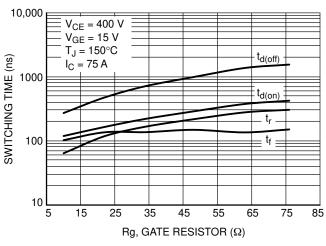


Figure 14. Switching Time vs. Rg

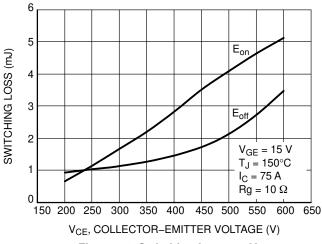


Figure 15. Switching Loss vs. V<sub>CE</sub>

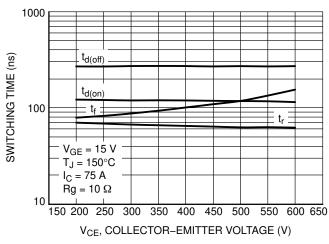


Figure 16. Switching Time vs. V<sub>CE</sub>

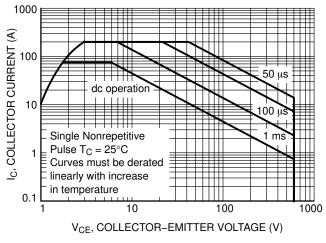


Figure 17. Safe Operating Area

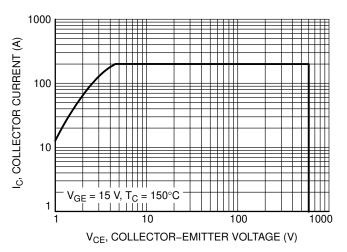
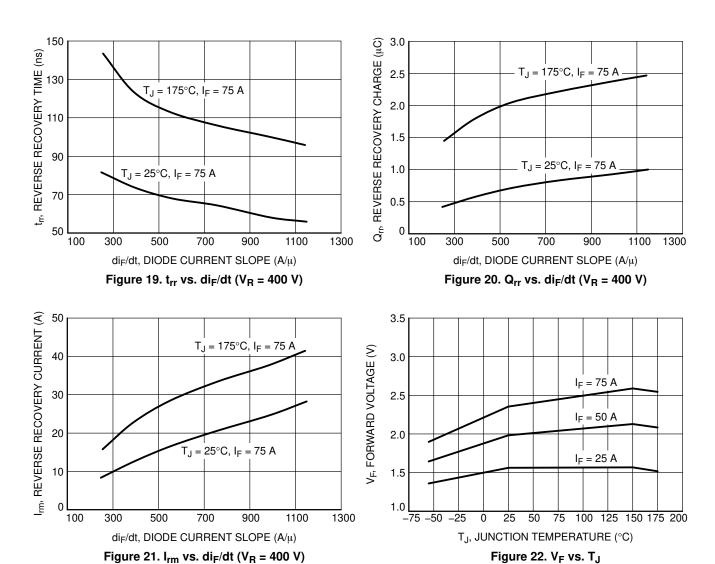


Figure 18. Reverse Bias Safe Operating Area



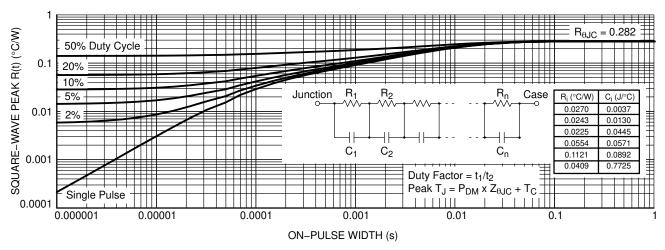


Figure 23. IGBT Transient Thermal Impedance

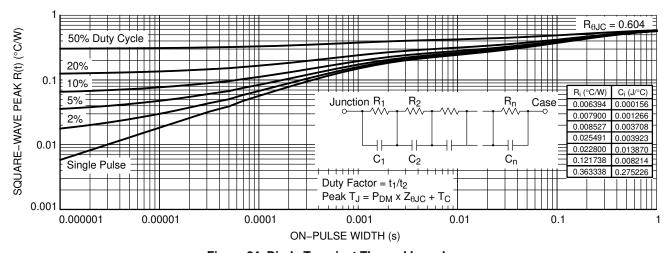
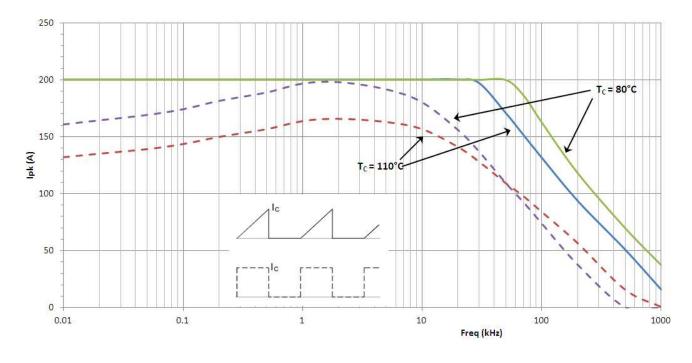


Figure 24. Diode Transient Thermal Impedance



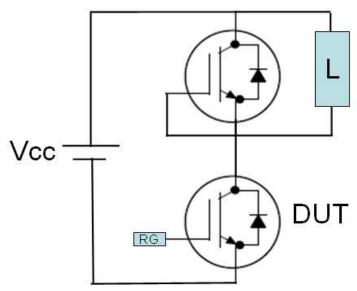


Figure 25. Test Circuit for Switching Characteristics

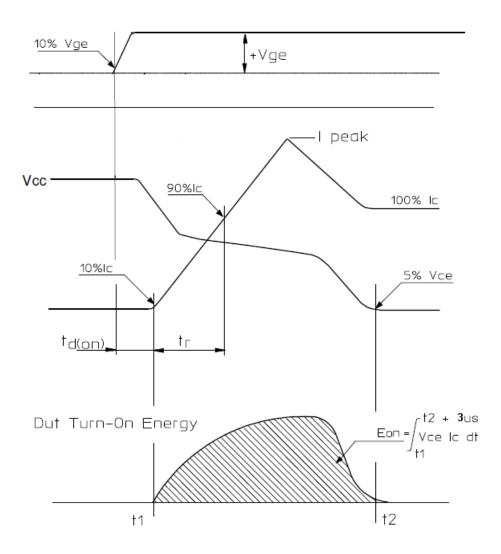


Figure 26. Definition of Turn On Waveform

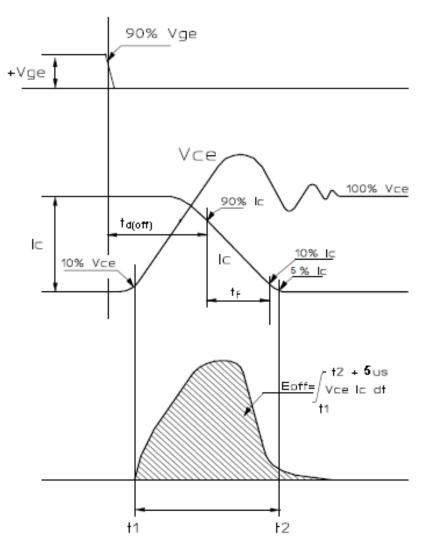
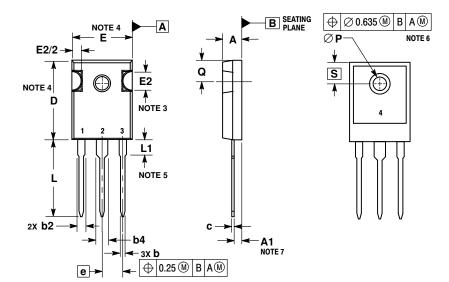


Figure 27. Definition of Turn Off Waveform

#### PACKAGE DIMENSIONS

TO-247 CASE 340AL **ISSUE B** 



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- SLOT REQUIRED, NOTCH MAY BE ROUNDED. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
  LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- $\varnothing$ P SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.
  DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.00	1.40	
b2	1.65	2.35	
b4	2.60	3.40	
C	0.40	0.80	
D	20.80	21.34	
Ε	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
L	19.80	20.80	
L1	3.81	4.32	
Р	3.55	3.65	
Q	5.40	6.20	
S	6.15 BSC		

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